

SOT2109-1

WLCSP74, wafer level chip scale package, 74 terminals, 0.4 mm pitch, 3.46 mm x 4.675 mm x 0.76 mm body

1 February 2021

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP74
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	07-10-2020
Manufacturer package code	98ASA01658D

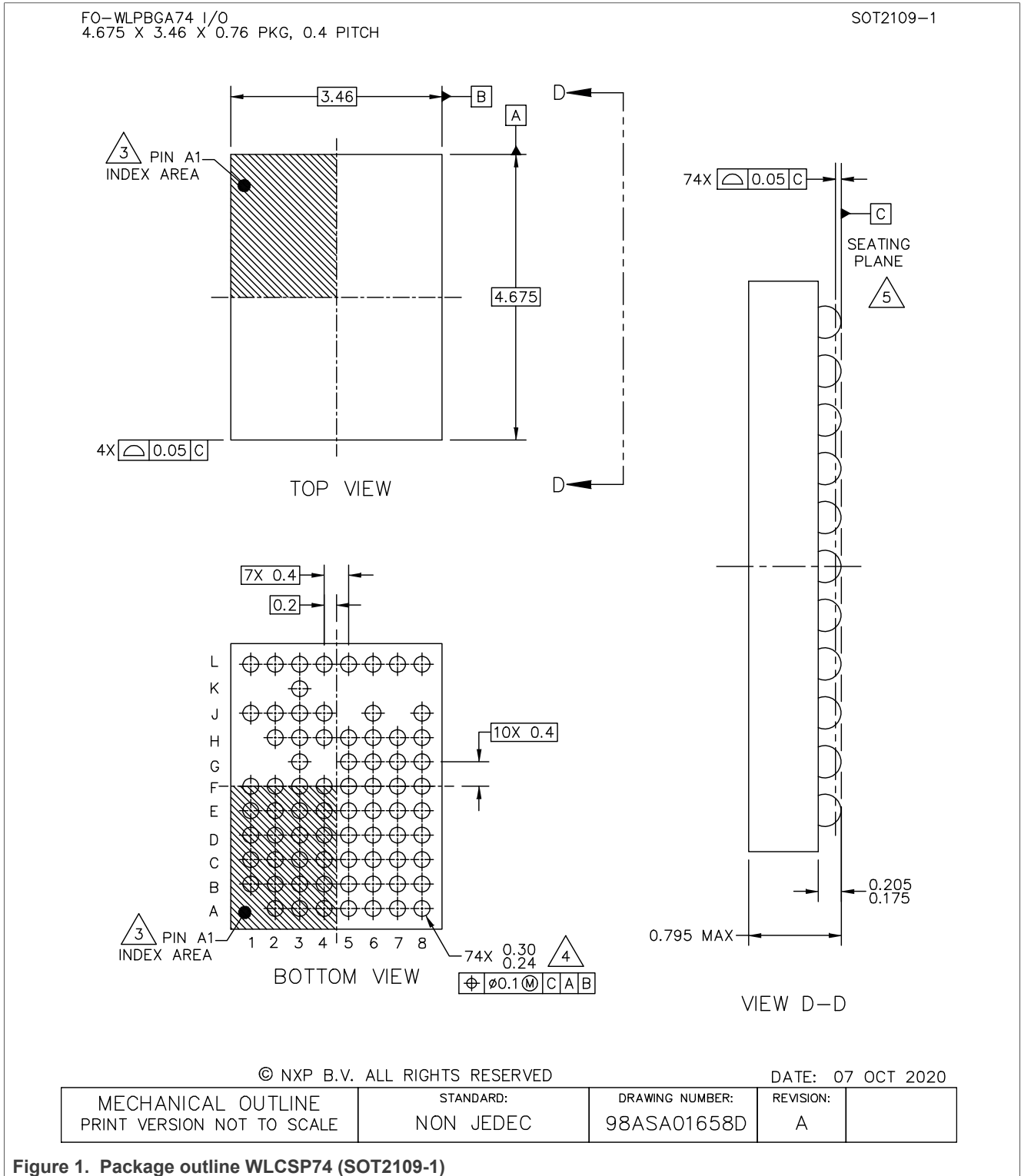
Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	3.41	3.46	3.51	mm
package width	4.625	4.675	4.725	mm
package height	-	0.76	0.795	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	74	-	



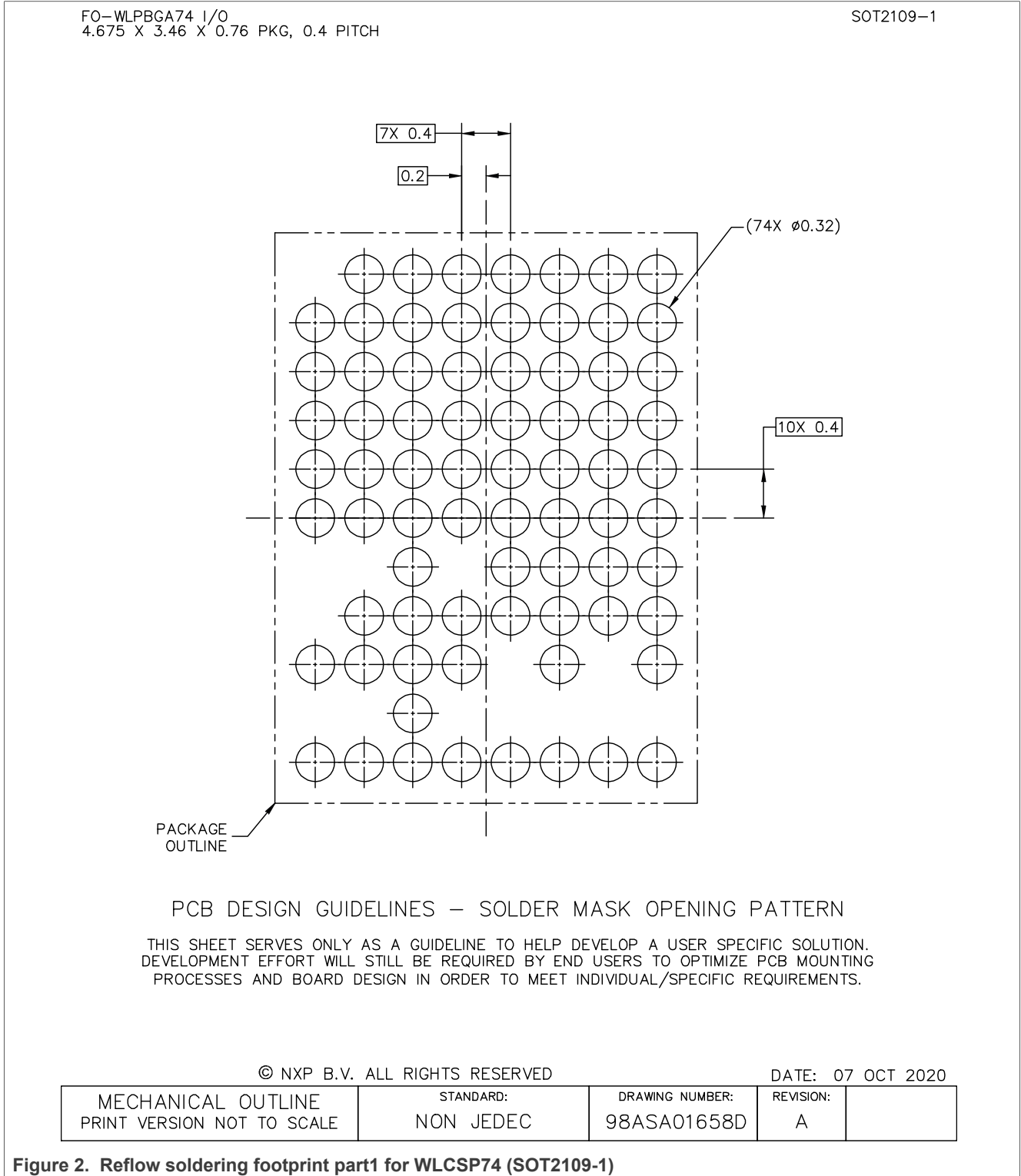
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2 Package outline

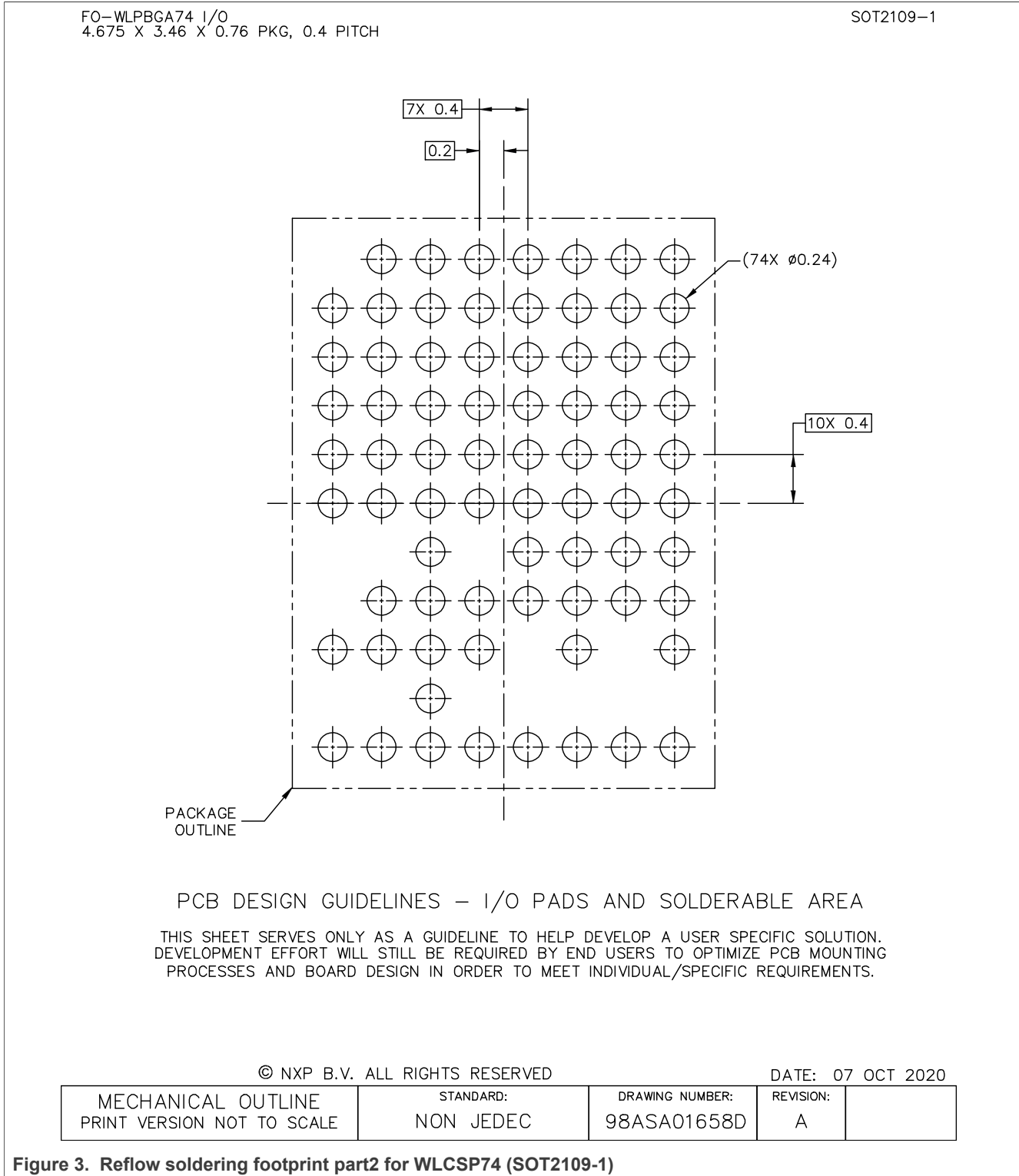


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3 Soldering



WLCSP74, wafer level chip scale package, 74 terminals, 0.4 mm pitch, 3.46 mm x 4.675 mm x 0.76 mm body



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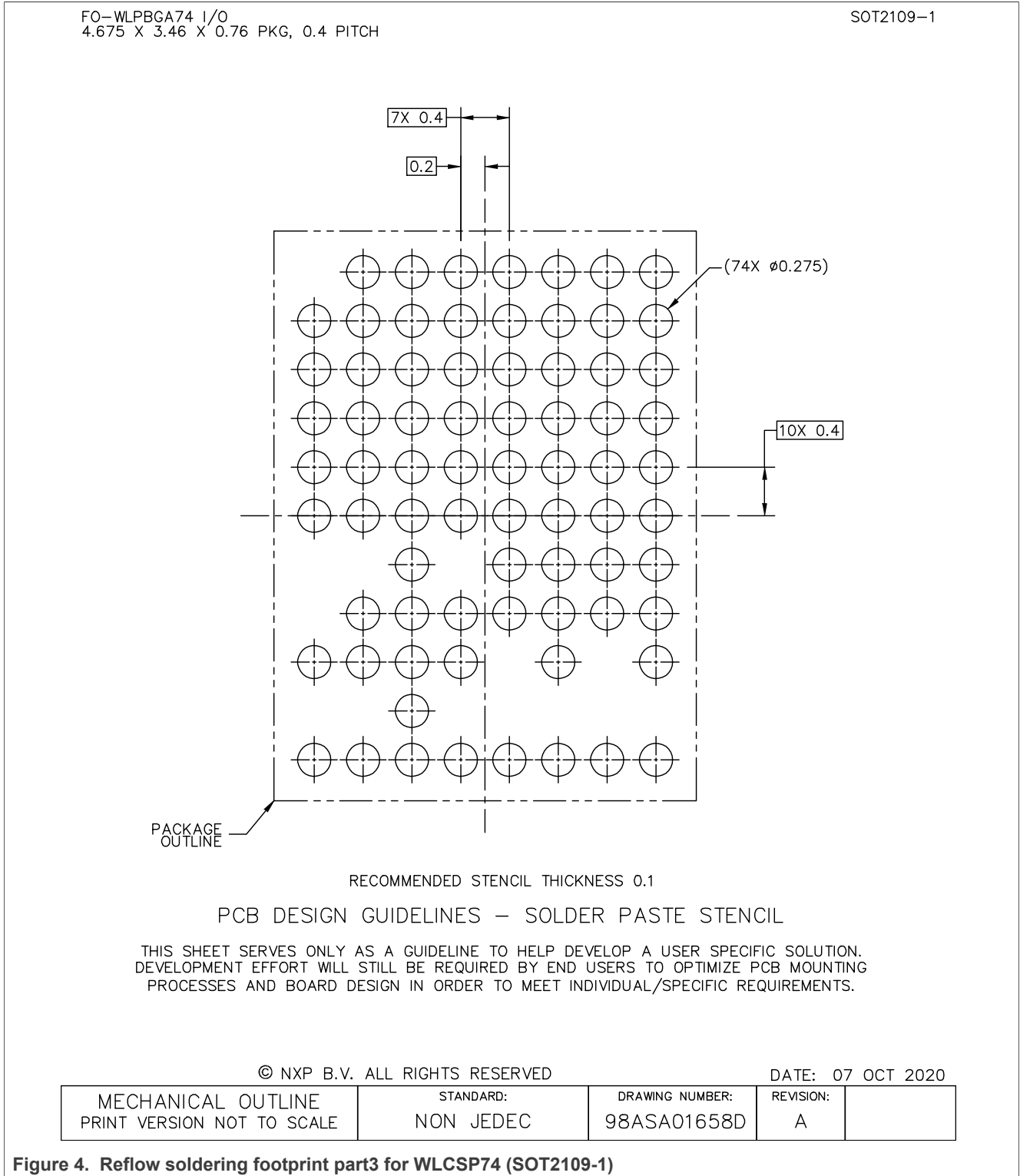


Figure 4. Reflow soldering footprint part3 for WLCSP74 (SOT2109-1)

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FO-WLPBGA74 I/O
4.675 X 3.46 X 0.76 PKG, 0.4 PITCH

SOT2109-1

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

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DATE: 07 OCT 2020

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01658D	REVISION: A	
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Figure 5. Package outline note WLCSP74 (SOT2109-1)

4 Legal information

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